

## Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

### **Quality Overview**

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
  - Class Q Military
  - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

# **General Purpose Transistors**

#### **PNP Silicon**

#### **Features**

• These are Pb-Free Devices\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	-60	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	-60	Vdc
Emitter - Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	-600	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

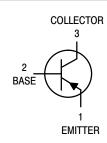
#### **DEVICE MARKING**

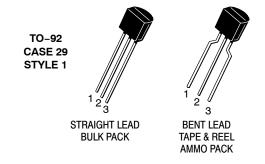
Device	Line 1	Line 2
MPS2907AG	MPS	2907A
MPS2907ARLG	MPS2	907A
MPS2907ARLRAG	MPS	2907
MPS2907ARLRPG	MPS	2907



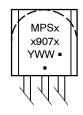
#### ON Semiconductor®

http://onsemi.com





#### **MARKING DIAGRAM**



Y = Year WW = Work Week ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

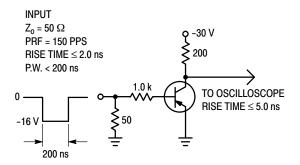
See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic			Min	Max	Unit
OFF CHARACTERISTICS			l .		
Collector - Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-60	-	Vdc	
Collector – Base Breakdown Voltage (I <sub>C</sub>	; = -10 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-60	-	Vdc
Emitter – Base Breakdown Voltage (I <sub>E</sub> =	-10 μAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-5.0	-	Vdc
Collector Cutoff Current (V <sub>CE</sub> = -30 Vd	c, V <sub>EB(off)</sub> = -0.5 Vdc)	I <sub>CEX</sub>	-	-50	nAdc
Collector Cutoff Current $(V_{CB} = -50 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -50 \text{ Vdc}, I_E = 0, T_A = 150^{\circ}\text{C})$			- -	-0.01 -10	μAdc
Base Current (V <sub>CE</sub> = -30 Vdc, V <sub>EB(off)</sub>	= -0.5 Vdc)	I <sub>B</sub>	-	-50	nAdc
ON CHARACTERISTICS		•		•	•
DC Current Gain $ \begin{array}{l} (I_C = -0.1 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -1.0 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -10 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -150 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -150 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -500 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (Note 1) \end{array} $		h <sub>FE</sub>	75 100 100 100 50	- - - 300 -	-
Collector – Emitter Saturation Voltage (Note 1) (I <sub>C</sub> = -150 mAdc, I <sub>B</sub> = -15 mAdc) (I <sub>C</sub> = -500 mAdc, I <sub>B</sub> = -50 mAdc)		V <sub>CE(sat)</sub>	- -	-0.4 -1.6	Vdc
Base – Emitter Saturation Voltage (Note 1)		V <sub>BE(sat)</sub>	- -	-1.3 -2.6	Vdc
SMALL-SIGNAL CHARACTERISTICS	3		l .	I.	
Current – Gain – Bandwidth Product (Notes 1 and 2), (I <sub>C</sub> = -50 mAdc, V <sub>CE</sub> = -20 Vdc, f = 100 MHz)		f <sub>T</sub>	200	_	MHz
Output Capacitance (V <sub>CB</sub> = -10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	8.0	pF
Input Capacitance (V <sub>EB</sub> = -2.0 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)		C <sub>ibo</sub>	-	30	pF
SWITCHING CHARACTERISTICS					
Turn-On Time	$(V_{CC} = -30 \text{ Vdc}, I_C = -150 \text{ mAdc},$	t <sub>on</sub>	-	45	ns
Delay Time	$I_{B1} = -15$ mAdc) (Figures 1 and 5)	t <sub>d</sub>	-	10	ns
Rise Time		t <sub>r</sub>	-	40	ns
Turn-Off Time	$(V_{CC} = -6.0 \text{ Vdc}, I_{C} = -150 \text{ mAdc},$	t <sub>off</sub>	-	100	ns
Storage Time	I <sub>B1</sub> = I <sub>B2</sub> = 15 mAdc) (Figure 2)	t <sub>s</sub>	-	80	ns
Fall Time		t <sub>f</sub>	-	30	ns

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2%. 2. f<sub>T</sub> is defined as the frequency at which  $|h_{fe}|$  extrapolates to unity.



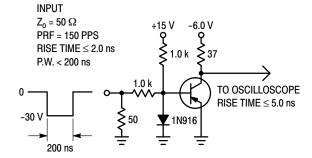


Figure 1. Delay and Rise Time Test Circuit

Figure 2. Storage and Fall Time Test Circuit

#### **TYPICAL CHARACTERISTICS**

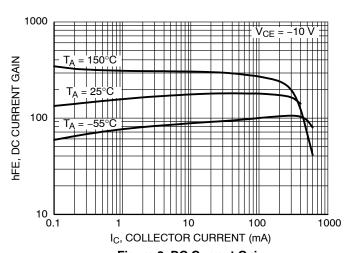


Figure 3. DC Current Gain

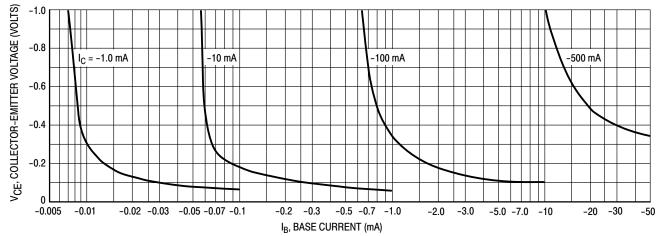


Figure 4. Collector Saturation Region

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
MPS2907AG	TO-92 (Pb-Free)	5000 Units / Bulk	
MPS2907ARLG	TO-92 (Pb-Free)	anno (Terre & Berel	
MPS2907ARLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel	
MPS2907ARLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

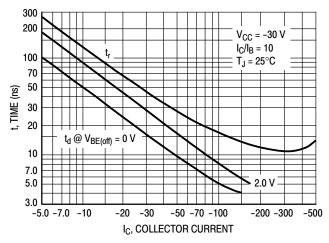


Figure 5. Turn-On Time

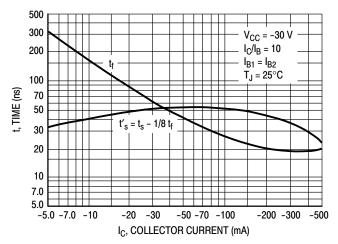


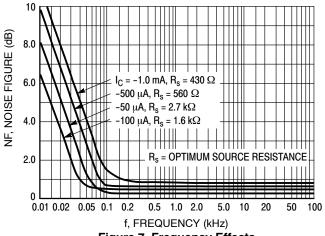
Figure 6. Turn-Off Time

### TYPICAL SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE}$  = 10 Vdc,  $T_A$  = 25°C

10

50 100 200



8.0 I<sub>C</sub> = -50 µA -100 µA -500 µA -1.0 mA

1.0 k

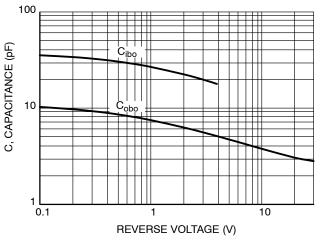
Figure 7. Frequency Effects

 $R_{\text{s}},$  SOURCE RESISTANCE  $(\Omega)$  Figure 8. Source Resistance Effects

2.0 k

5.0 k

50 k



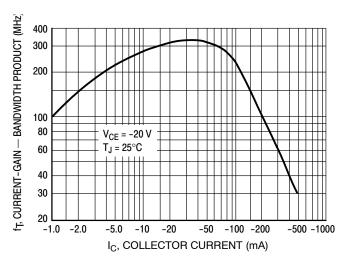
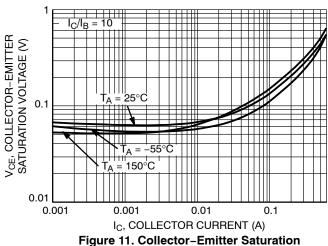


Figure 9. Capacitances

Figure 10. Current-Gain - Bandwidth Product



Voltage vs. Collector Current

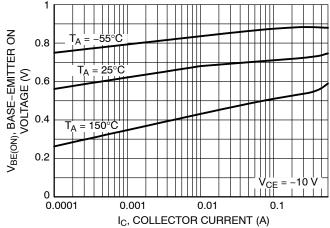
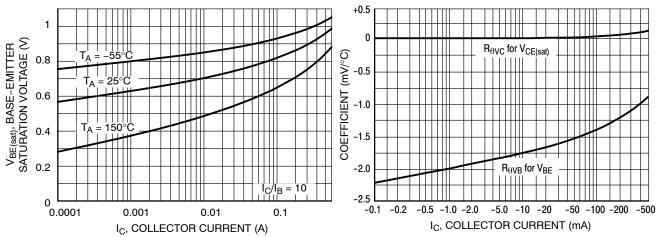


Figure 12. Base-Emitter Turn-ON Voltage vs.
Collector Current



I<sub>C</sub>, COLLECTOR CURRENT (A)

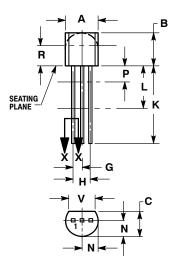
Figure 13. Base Emitter Saturation Voltage vs.

Collector Current

Figure 14. Temperature Coefficients

#### PACKAGE DIMENSIONS

#### TO-92 (TO-226) CASE 29-11 ISSUE AM



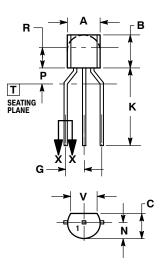
STRAIGHT LEAD **BULK PACK** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	



**BENT LEAD** TAPE & REEL AMMO PACK



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. CONTOUR OF PACKAGE BEYOND
- DIMENSION R IS UNCONTROLLED. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
V	2 //2		

STYLE 1:

PIN 1. EMITTER

BASE

COLLECTOR

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, ON semiconductor and war registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC wors the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent—Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implications the polar or other applications intended to surgical implication in which the failure of the SCILLC products could create a situation where surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

**Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative